

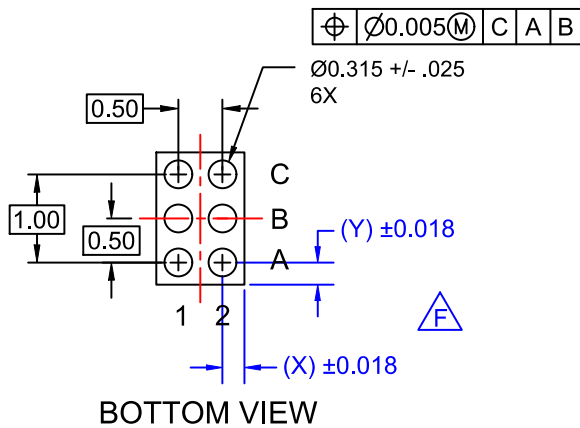
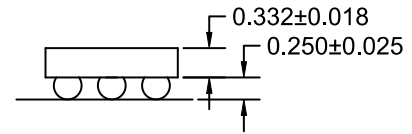
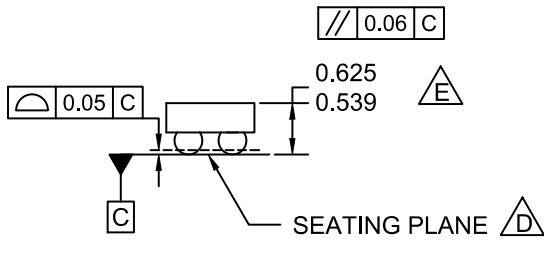
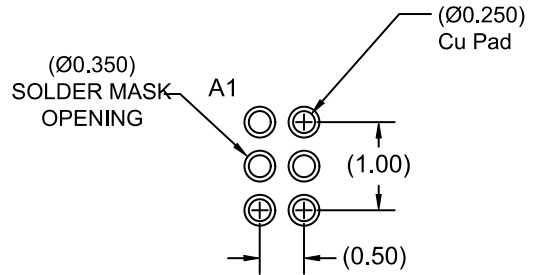
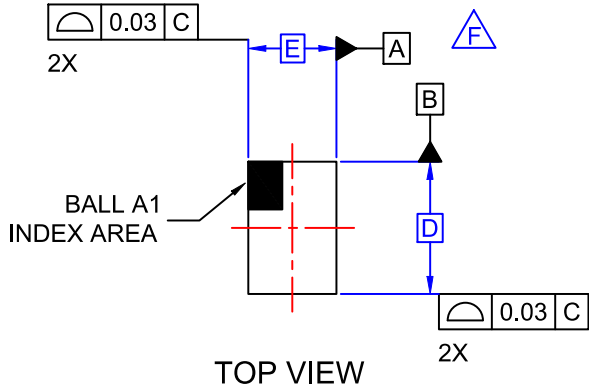
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®



WLCSP6 1.5x1.0x0.582
CASE 567RL
ISSUE O

DATE 30 NOV 2016



NOTES:

- A. NO JEDEC REGISTRATION APPLIES.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCE PER ASMEY14.5M, 1994.
- D.** DATUM C IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.
- E.** PACKAGE NOMINAL HEIGHT IS 582 MICRONS ±43 MICRONS (539-625 MICRONS).
- F.** FOR DIMENSIONS D, E, X, AND Y SEE PRODUCT DATASHEET.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	WLCSP6 1.5x1.0x0.582	PAGE 1 OF 2

